

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD60N10S4L-12	**Issued**	02. June 2021
MA#	MA001620526		
Package	PG-TO252-3-313	**Weight***	319.67 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.510	0.79	0.79	7853	7853
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		138	
	non noble metal	iron	7439-89-6	0.147	0.05		461	
	non noble metal	copper	7440-50-8	147.096	46.01	46.07	460154	460753
wire	non noble metal	aluminium	7429-90-5	5.335	1.67	1.67	16688	16688
encapsulation	inorganic material	zincoxide	1314-13-2	1.379	0.43		4313	
	miscellaneous	miscellaneous	-	6.893	2.16		21563	
	plastics	epoxy resin	-	20.679	6.47		64688	
	inorganic material	silicondioxide	60676-86-0	108.907	34.07	43.13	340689	431253
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11700	11700
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4444	4455
solder	non noble metal	tin	7440-31-5	0.046	0.01		145	
	noble metal	silver	7440-22-4	0.058	0.02		181	
	non noble metal	lead	7439-92-1	2.206	0.69	0.72	6902	7228
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.00	6.01	59992	60070
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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